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FPF2411 — IntelliMAX™ 6 V / 6 A - Rated Bi-Directional Switch with Slew Rate Control and RCB

Features

- Capability: 6 V
- Low R_{ON}
 - 10 mΩ at 5 V at PWRA or PWRB (Typ.)
 - 12 m Ω at 3.8 V at PWRA or PWRB (Typ.)
- Maximum Current Capability: 6 A (Bi-Directional)
- Ultra-Low I_O:<1 µA</p>
- Active LOW Control Pin
- 2 ms Long Slew Rate
- Reverse Current Blocking (RCB) during OFF
- Robust ESD Capability:
 - 5 kV HBM, 2 kV CDM
 - 15 kV Air Discharge
 - 8 kV Contact Discharge Under IEC 61000-4-2

Applications

- Smartphone / Tablet PC
- Mobile Devices
- Portable Media Devices

Description

The FPF2411 is a $6\,V/6\,A$ -rated bi-directional load switch, consisting of a slew-rate-controlled, low-on-resistance, P-channel MOSFET switch with protection features. The slew-rate-controlled turn-on characteristic prevents inrush current and the resulting excessive voltage droop on the input power rails. The input voltage range operates from $2.3\,V$ to $5.5\,V$.

Bi-directional switching allows reverse current from V_{OUT} to V_{IN} . The switching is controlled by active-LOW logic input the ONB pin. The FPF2411 is capable of interfacing directly with low-voltage control signal General-Purpose Input / Output (GPIO).

The FPF2411 is available in 12-bump, 1.235 mm \times 1.625 mm Wafer-Level Chip-Scale Package (WLCSP) with 0.4 mm pitch.

Ordering Information

Part Number	Top Mark	R _{ON} (Typ.) at 3.8 V _{IN}	Output Discharge	ONB Pin Functionality	Package
FPF2411BUCX_F130	QR	12 mΩ	No		12-Ball Wafer-Level Chip-Scale Package (WLCSP), 3 x 4 Array, 0.4 mm Pitch, 250 µm Ball

Application Diagrams

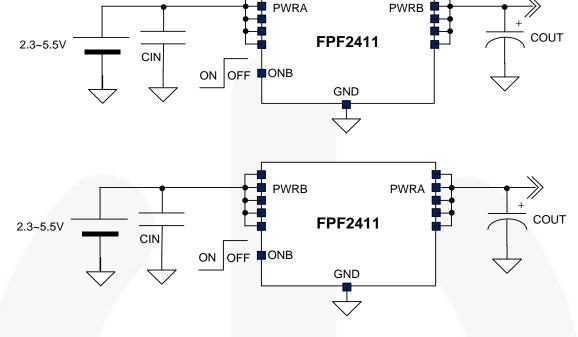
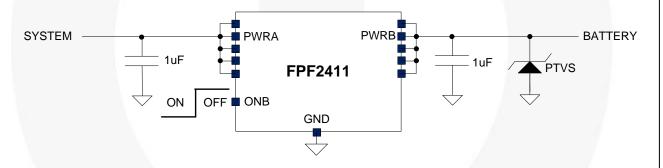


Figure 1. High-Level Application Diagrams



Note: Adding a PTVS such as RDP3101B is recommended at PWRB node in order to avoid device damage from surge or equivalent stress.

Figure 2. Battery Isolation Application

Block Diagrams

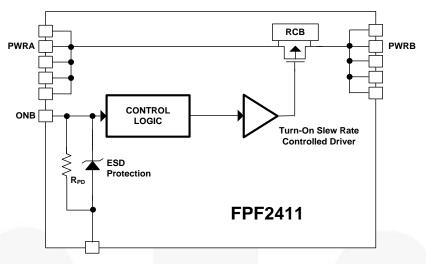


Figure 3. Block Diagram

Application Scenario

Table 1. PWRA and PWRB can be Input or Output, Depending on Scenario

PWRA	PWRB	ONB	Operations
	7		OFF state
X	X	HIGH	PWRA and PWRB are isolated.
			Current more than I _{SD} or I _{RCB} is NOT allowed.
2.3~5.5 V	Open	HIGH → LOW	Turn-on with 2 ms of t _R at PWRB.
Open	2.3~5.5 V	HIGH → LOW	Turn-on with 2 ms of t _R at PWRA.
			ON state
2.3~5.5 V	Open	LOW	Operating current is from PWRA.
	A		No problem with 6 A DC current flowing.
			ON state
Open	2.3~5.5 V	LOW	Operating current is from PWRB.
			No problem with 6 A DC current flowing.
2.3~5.5 V	Open	LOW → HIGH	Turn-off with 1 ms of t _F at PWRB.
Open	2.3~5.5 V	LOW → HIGH	Turn-off with 1 ms of t _F at PWRA.

Note:

1. X = Don't care.

Timing Diagrams

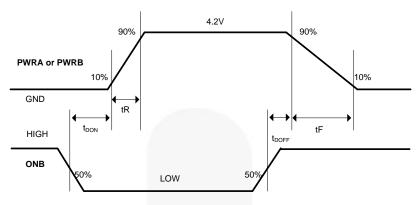


Figure 4. Dynamic Behavior

Pin Configuration

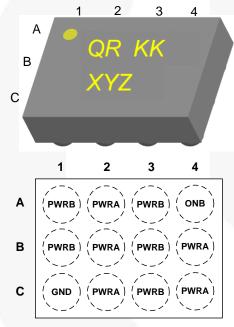


Figure 5. Top View

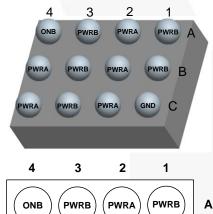




Figure 6. Bottom View

Pin Descriptions

Pin #	Name	Description
A2, B2, B4, C2, C4	PWRA	Power Input / Output: Bi-directional power path
A1, A3, B1, B3, C3	PWRB	Power Input / Output: Bi-directional power path
C1	GND	Ground
A4	ONB	ON/OFF Control Input: Active LOW.

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol		Parameter	Min.	Max.	Unit
V _{PIN}	PWRA, PWRB, ONB to GND	PWRA, PWRB, ONB to GND			
I _{SW}	Maximum Continuous Switch	Maximum Continuous Switch Current			
t _{PD}	Total Power Dissipation at T _A	Total Power Dissipation at T _A =25°C			
TJ	Operating Junction Temperat	-40	+150	°C	
T_{STG}	Storage Junction Temperatur	-65	+150	ů	
Θ_{JA}	Thermal Resistance, Junction	n-to-Ambient (1in. ² Pad of 2 oz. Copper)		84.1 ⁽²⁾	°C/W
	Electrostatic Discharge	Human Body Model, JESD22-A114	5		
ESD	Capability	Charged Device Model, JESD22-C101 Air Discharge (PWRA, PWRB, ONB to GND)			kV
	IEC61000-4-2 System Level				l V
- 1	1EC01000-4-2 System Level	Contact Discharge (PWRA, PWRB, ONB to GND)	8		

Note:

2. Measured using 2S2P JEDEC std. PCB.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Max.	Unit
V _{PWRn}	PWRA, PWRB	2.3	5.5	V
T _A	Ambient Operating Temperature	-40	85	°C

DC / AC Characteristics

Unless otherwise noted, V_{IN} =2.3 to 5.5 V, T_A =-40 to 85°C; typical values are at PWRA or PWRB=4.2 V and T_A =25°C.

Symbol	Parameter	Condition	Min.	Тур.	Max.	Unit
V _{PWRA}	Input Voltage		2.3		5.5	V
I _{SD}	Shutdown Current	PWRA=ONB=5.5 V, PWRB=Open OR PWRB=ONB=5.5 V, PWRA=Open			1	μΑ
I _{PWRA} I _{PWRB}	Quiescent Current	ONB=GND, I _{OUT} =0 mA			1	μΑ
В	On-Resistance	PWRA, PWRB=3.8 V, I _{OUT} =200 mA, T _A =25°C		12	17	mΩ
R _{ON}	On-Resistance	PWRA, PWRB=5 V, I _{OUT} =200 mA, T _A =25°C		10	16	11122
ViH	ONB, Input Logic HIGH	PWRn=4.5 V, I_{LOAD} =50 μ A, T_{A} (Max.) = 60°C	4.3			
VIH	Voltage ⁽³⁾	PWRn=3.6 V, I_{LOAD} =50 μ A, T_{A} (Max.) = 60°C	3.4			V
VIL	ONB, Input Logic LOW Voltage ⁽³⁾	PWRn=4.5 V, I_{LOAD} =50 μ A, T_{A} (Max.) = 60°C			0.4	V
VIL	Voltage ⁽³⁾	PWRn=3.6 V, I_{LOAD} =50 μ A, T_{A} (Max.) = 60°C			0.4	
R _{PD}	Pull-Down Resistance at ONB			500	700	kΩ
Dynamic	Characteristics: see definition	s below				
t _{DON}	Turn-On Delay ^(4,5,6)		1	1.5		
t _R	Rise Time ^(4,5,6)	PWRA or PWRB =4.2 V, R_L =10 Ω , C_L =1 μ F, ONB=HIGH to LOW		3.0		ms
t _{ON}	Turn-On Time ^(4,5,6)	- OND-INGITIO LOW		4.5		
t _{DOFF}	Turn-Off Delay ^(4,5,7)			5.5		
t _F	Fall Time ^(4,5,7)	PWRA or PWRB =4.2 V, R_L =100 Ω , C_L =1 μ F, ONB=LOW to HIGH		1.0		ms
t _{OFF}	Turn-Off Time ^(4,5,7)	OND-LOW TO FROM		6.5		

Notes:

- 3. V_{IH}/V_{IL} is tested under 50 µA current load
- 4. This parameter is guaranteed by design and characterization; not production tested.
- 5. t_{DON}/t_{DOFF}/t_R/t_F are defined in Figure 4.
- 6. $t_{ON}=t_R + t_{DON}$
- 7. $t_{OFF}=t_F+t_{DOFF}$.

Table 2. V_{IH} / V_{IL} [V]

I _{LOAD} \ V _{BAT}	2.7 V	3.7 V	4.35 V
0.1 mA	1.8 / 0.7	2.9 / 0.9	3.4 / 1.0
1 mA	1.1 / 0.7	2.1 / 0.9	2.8 / 1.0
3 mA	1.1 / 0.7	2.1 / 0.9	2.7 / 1.0
5 mA	1.0 / 0.7	2.0 / 0.9	2.7 / 1.0
10 mA	0.9 / 0.7	1.9 / 0.8	2.4 / 0.9
30 mA	0.9 / 0.7	1.5 / 0.8	2.2 / 0.9
50 mA	0.9 / 0.7	1.2 / 0.8	1.9 / 0.9
100 mA	0.9 / 0.7	1.0 / 0.8	1.1 / 0.9

Typical Performance Characteristics

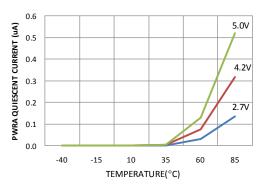


Figure 7. PWRA Quiescent Supply Current vs. Temperature

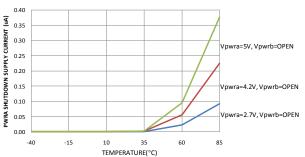


Figure 9. PWRA Shutdown Supply Current vs. Temperature

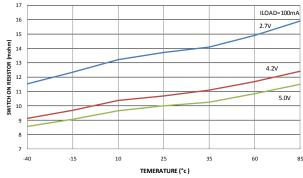


Figure 11. Switch On Resistance vs. Temperature

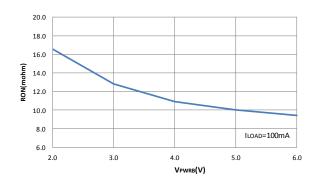


Figure 13. On Resistance vs. PWRB Voltage

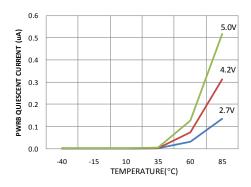


Figure 8. PWRB Quiescent Supply Current vs. Temperature

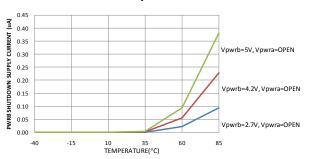


Figure 10. PWRB Shutdown Supply Current vs. Temperature

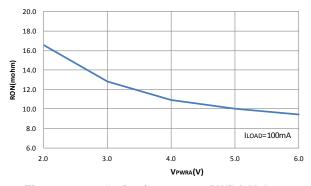


Figure 12. On Resistance vs. PWRA Voltage

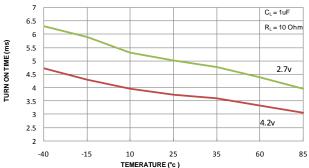
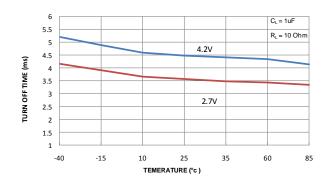


Figure 14. Switch On Time vs. Temperature

Typical Performance Characteristics (Continued)



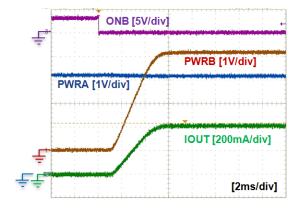
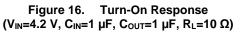


Figure 15. Switch Off Time vs. Temperature



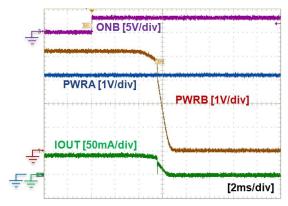


Figure 17. Turn-OFF Response (V_{IN} =4.2 V, C_{IN} =1 μ F, C_{OUT} =1 μ F, R_L =100 Ω)

Operation and Application Description

The FPF2411 is an ultra-low- R_{ON} P-channel load switch with bi-directional controlled turn-on and Reverse Current Blocking (RCB). The core is a 12 m Ω P-channel MOSFET and controller capable of functioning over a wide input operating range of 2.3 V to 5.5 V. The ONB pin, active-LOW; controls the state of the switch. RCB functionality blocks unwanted reverse current during OFF states by power switch isolation between PWRA and PWRB.

Inrush Current

Inrush current occurs when the device is turned on. Inrush current is dependent on output capacitance and slew rate control capability, as expressed by:

$$I_{\mathit{INRUSH}} = C_{\mathit{OUT}} \times \frac{V_{\mathit{IN}} - V_{\mathit{INITIAL}}}{t_{\mathit{R}}} + I_{\mathit{LOAD}}$$

where:

C_{OUT}: Output capacitance;

t_R: Slew rate or rise time at V_{OUT};

V_{IN}: Input voltage;

VINITIAL: Initial voltage at Cout, usually GND; and

ILOAD: Load current.

Higher inrush current causes higher input voltage drop, depending on the distributed input resistance and input capacitance. High inrush current can cause problems.

FPF2411 has a 3 ms of slew rate capability under 4.2 V_{IN} at 1 μF of C_{OUT} and 10 Ω of R_L . Inrush current can be minimized and no input voltage drop appears, as shown in Figure 16.

Reverse-Current Blocking

The reverse-current blocking feature protects the input source against current flow from output to input when the load switch is off by changing the internal body diode direction.

Bypass Capacitor

To limit the voltage drop on the input supply caused by transient inrush current when the switch turns on into a discharged load capacitor; a capacitor must be placed between the PWRA or PWRB and GND pins. A ceramic capacitor of at least 1 μF placed close to the pins is usually sufficient.

Board Layout

For best performance, all traces should be as short as possible. To be most effective, the input and output capacitors should be placed close to the device to minimize the effect that parasitic trace inductance on normal and short-circuit operation. Using wide traces or large copper planes for all pins (PWRA, PWRB, ONB, and GND) minimizes the parasitic electrical effects and the case-to-ambient thermal impedance.

WLCSP Packing - Embossed Tape FPF2411BUCX Pin1 at 1 o'clock Rev0

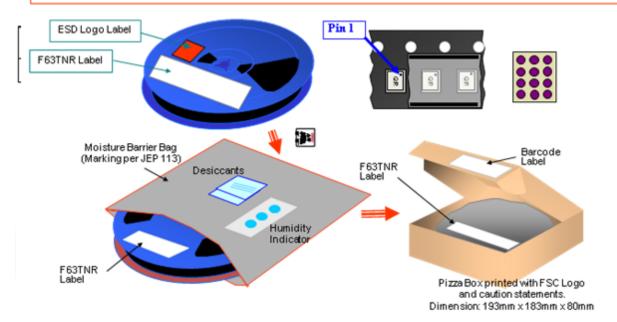


Packing Description:

WLCSP products are classified under Moisture Sensitive Level 1 and are packed in moisture barrier bag for added protection.

The carrier tape is made from dissipative polystyrene or polycarbonate resin. The cover tape is a multilayer film primarily composed of polyester film, adhesive layer, heat activated sealant, and anti-static sprayed agent. These rected parts in standard option are shipped with 3000 units per 178 mm diameter red. Up to three rects are packed in each intermediate box. The rects is made of polystyrene plastic (anti-static coated or intrinsic).

These full reels are individually barcode labeled and placed inside a pizza box made of recyclable corrugated brown paper with a Fairchild logo printing. The reel is packed single reel in the pizza box. And these pizza boxes are placed inside a barcode labeled shipping box which comes in different sizes depending on the number of parts shipped.



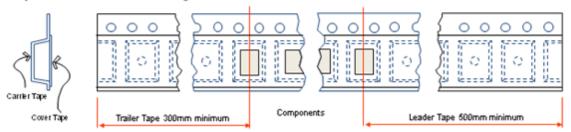
ESD Logo Label sample



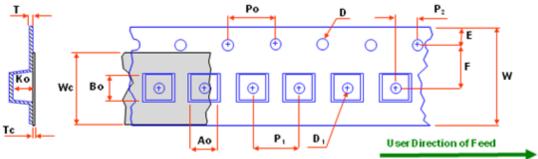
F63TNR Label sample



Tape Leader and Trailer Configuration



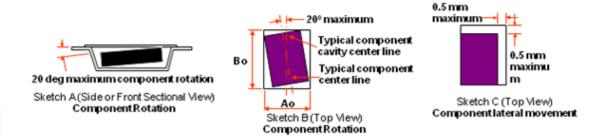
WLCSP Embossed Tape Dimension

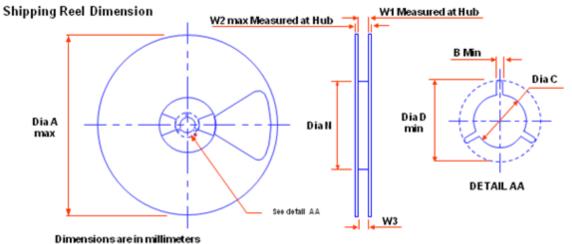


Dimensions are in millimeters

Package	Ao +/-0.05	Bo +/-0.05					Ko +/-0.05				T TYP	Tc +/-0.005		Wc TYP
FPF2411UCX	1.55	1.95	1.50	0.5	1.75	3.5	0.75	4	4	2.0	0.25	0.06	8	5.3

Notes: Ao, Bo, and Ko dimensions are determined with respect to the EIA/JEDEC RS-481 rotational and lateral movement requirements (see sketches A, B, and C).





TapeVVidth	Dia A max	Dim B min	Dia C +.5/2		Dim N min	Dim W1 +2/-0	Dim W2 max	Dim W3 (LSL - USL)
8	178	1.5	13	20.2	55	8.4	14.4	7.9~10.4

Rev1,25102011

Physical Dimensions 0.03 C (Ø0.215) 1.20 Cu Pad 0.80 $\bigcirc \bigcirc \bigcirc \bigcirc$ 0.40 PIN 1 AREA 12X 0.20 (Ø0.315) Solder Mask △ 0.03 C **TOP VIEW** RECOMMENDED LAND PATTERN (NSMD PAD TYPE) -0.378±0.018 0.208±0.021 C SEATING PLANE SIDE VIEWS NOTES: A. NO JEDEC REGISTRATION APPLIES. ⊕ 0.005∭ C A B B. DIMENSIONS ARE IN MILLIMETERS. 1.20 Ø0.260±0.02 C. DIMENSIONS AND TOLERANCES PER 0.20 ASME Y14.5M, 2009. 12X D. DATUM C IS DEFINED BY THE SPHERICAL | ⊕ ⊕ | O ⊕ | **c** CROWNS OF THE BALLS. ┌ (Y)±0.018 0.80 0 0 0 B PACKAGE NOMINAL HEIGHT IS 586 MICRONS

12-Ball, 3x4 Array, 0.4 mm Pitch, 250 µm Ball, Wafer-Level Chip-Scale Package (WLCSP)

±39 MICRONS (547-625 MICRONS).

PRODUCT DATASHEET.

LAND, NOT THE TOP EDGE.

FOR DIMENSIONS D, E, X, AND Y SEE

G. DRAWING FILENAME: MKT-UC012ZCrev2.

H. FAIRCHILD SEMICONDUCTOR RECOMMENDS THAT

LANDS IN THE LANDPATTERN ARE AT LEAST .215MM DIAMETER AS MEASURED AT THE BOTTOM OF THE

Nominal Values

Bump	Overall Package	Silicon	Solder Bump	Solder Bump
Pitch	Height	Thickness	Height	Diameter
0.4 mm	0.586 mm	0.378 mm	0.208 mm	0.260 mm

Product-Specific Dimensions

 $\oplus \bigcirc \oplus \oplus \blacktriangle$

 $(X)\pm0.018$

2 3

BOTTOM VIEW

Product	D	E	X	Y
FPF2411BUCX_F130	1.235 mm	1.625 mm	0.2125 mm	0.2175 mm





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- 2. A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
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